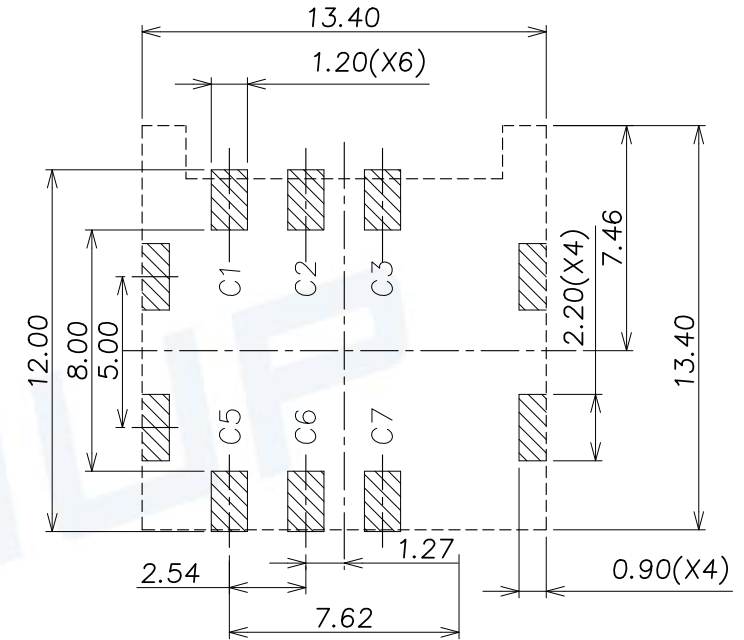
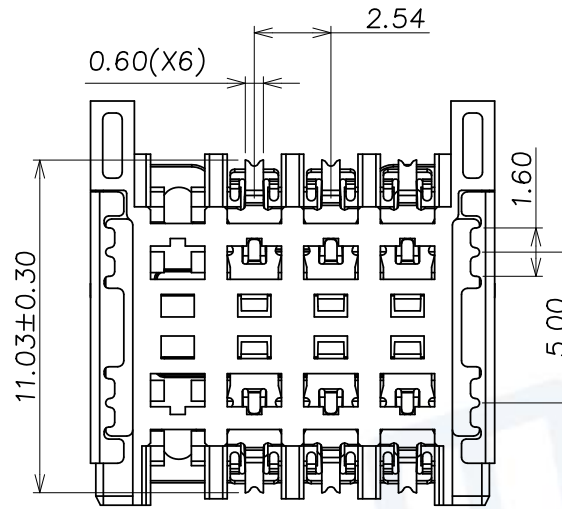
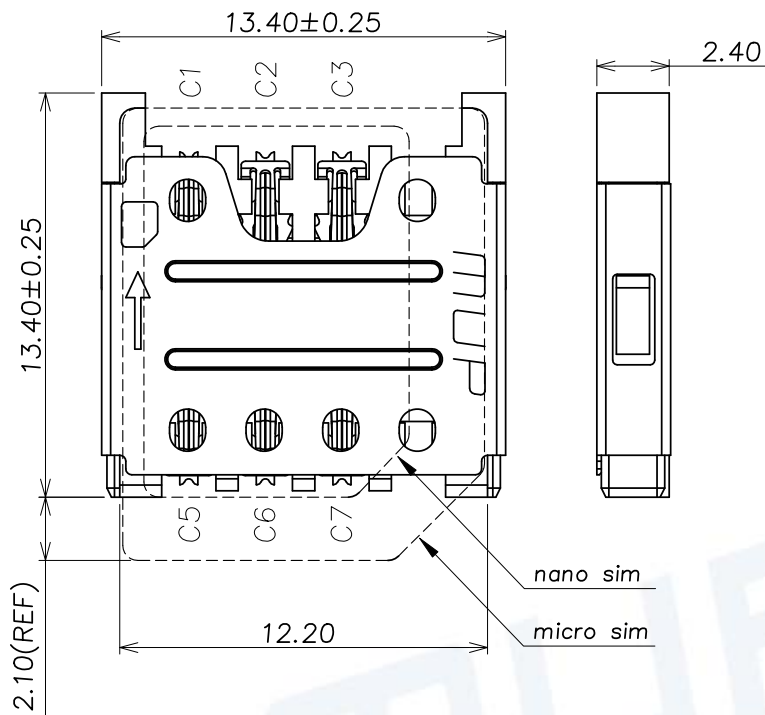
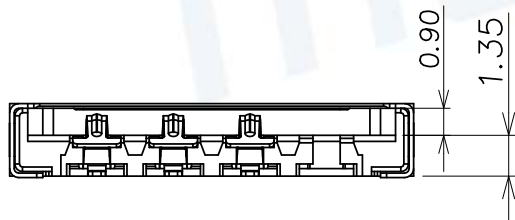


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)



#### TECHNICAL CHARACTERISTICS

- General Characteristics  
Dimensions: 13.40LX13.40WX2.40H mm  
Durability: 5,000 cycles min.
- Electrical Characteristics  
Contact resistance: 50mΩ typical, 100mΩ max  
Insulation resistance: >1000MΩ/500V DC
- Solderability  
Vapor phase: 215°C, 30sec. Max  
IR reflow: 250°C, 5sec. Max  
Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics  
Operating temperature: -40°C~+85°C  
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5°
X.X	±0.25	X.X*	±4°
X.XX	±0.15	X.XX*	±3°
X.XXX	±0.10	X.XXX*	±2°

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **Micro-SIM Card Connector**

MODEL NO: **MUP C790-25**

TYPE: **H2.40 Without post 6p**

PROJ.	UNIT	SCALE	DRAWN	HUABO Jun.15.2021	DWG NO.:
⊕	MM	1:1	CHECKED	Sean Jun.15.2021	DWG-MUP-C790-025
CUSTOMER DRAWING			APPROVAL	Simon Jun.15.2021	SHEET 1/1
					REVISION X1

